ABSTRACT

A raw sheet L, in which a strip-shaped tape base material TB having a die bonding sheet portion DS with a size of substantially corresponding to the shape of a semiconductor wafer W is temporarily stuck to a strip-shaped release liner S, is fed out, and the position of the die bonding sheet portion DS is identified on the pathway of feeding out. Based on the identified result, a die cutting device 13 provides a closed-loop-shaped cut-line C to be encircling the die bonding sheet portion DS corresponding to the shape of the ring frame RF to form a sticking tape DDT. The sticking tape DDT is peeled by a peeling device 15 to be stuck to the ring frame RF in the position that the die bonding sheet portion DS is to be corresponding to the semiconductor wafer W.